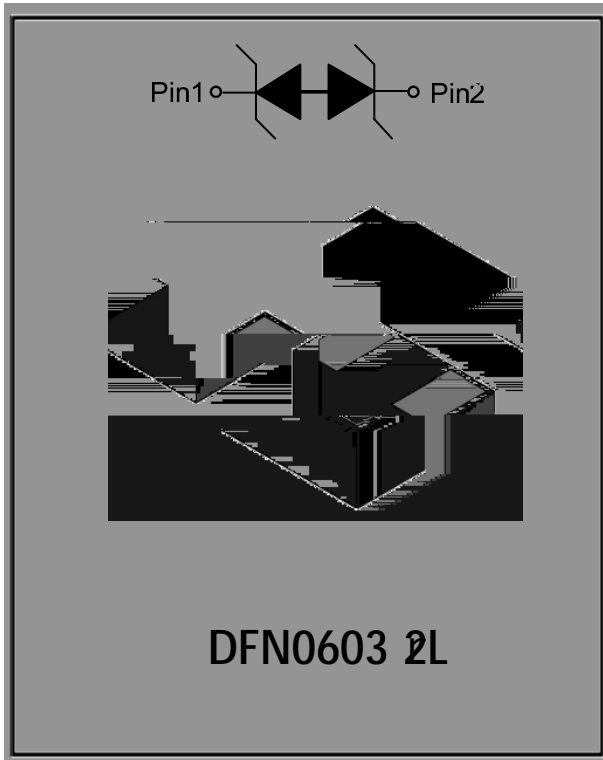


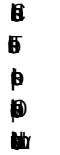
1- L aBit



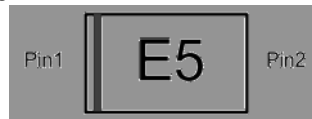
Fa



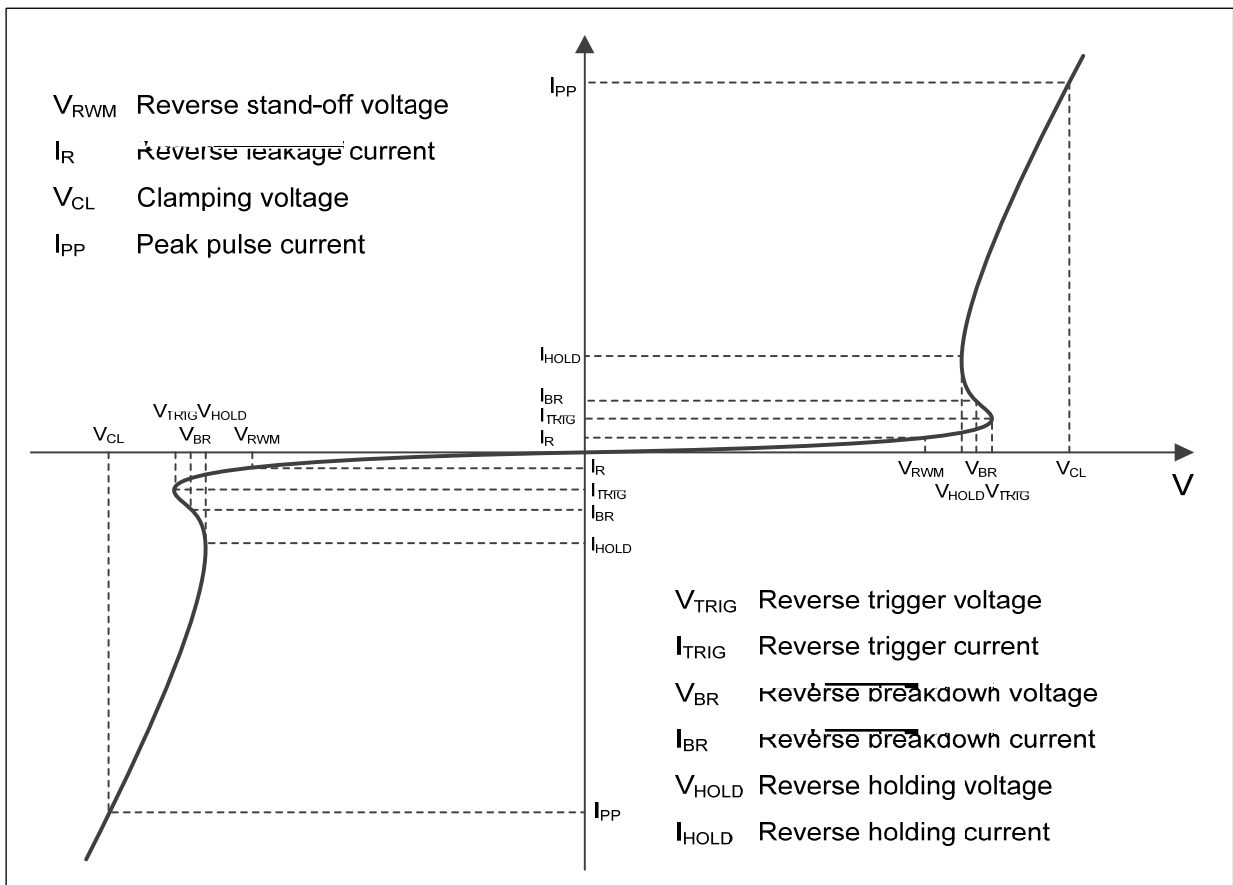
Ap



MCb



Di





EB50 L BA

Table 1 (continued)

Parameter	Symbol	Rating	Unit
Maximum power	P_{max}	2	W
Rated power	P_r	6	A
Voltage	V_B	9	V
		9	V
Temperature	T_J	2	$^{\circ}C$
Temperature	T_{θ}	9	$^{\circ}C$
Temperature	T	9	$^{\circ}C$

Table 2 (continued)

Parameter	Symbol	Min	Max	Min	Max
Voltage	V			6	
Current	I		1.5	0	
Voltage	V_B	3	1.5		7
		3	1.5		7
1)	V_C		1.5	7	
1)	R_{θ}			0	
2)	V_C		1.5	8	
3)	V_C		1.5	6	7
			1.5	8	5
			1.5	8	9
4)	C_J	1.5	1.5	3	5
		1.5	1.5	2	5

Notes: 1) For V_C and R_{θ} , see Table 1. 2) For V_C , see Table 1. 3) For V_C , see Table 1. 4) For C_J , see Table 1.



ED5V

L

BA

$\sqrt{0.6}$

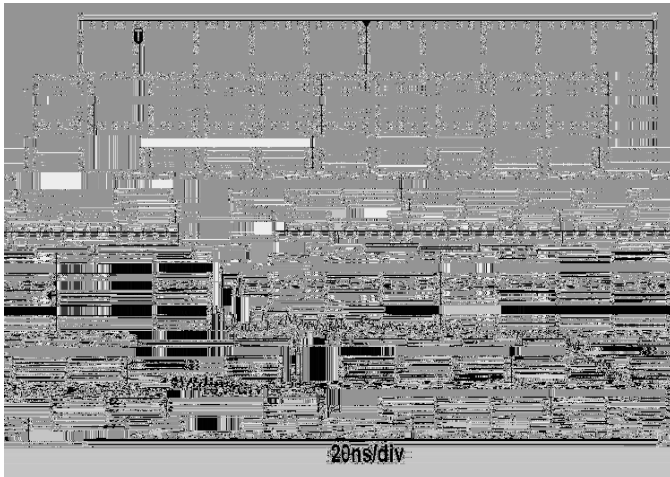
$\frac{1}{2}$

$\frac{1}{2}$

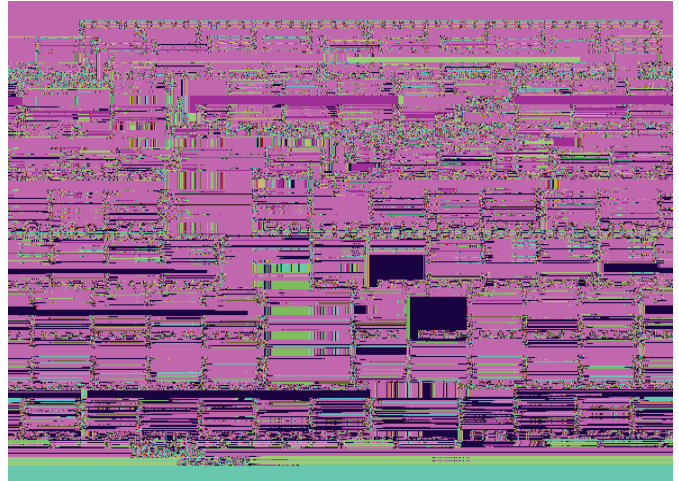
8/20 μ s waveform per IEC61000 4 5

Contact discharge, $U_{sp} = 1.2 U_n$, U_{sp} Chart 506 1000 r

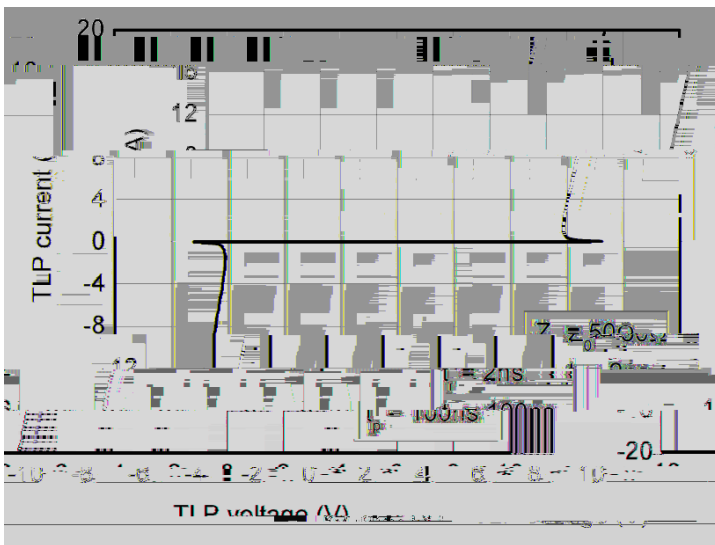
ESD clamping
(+8kV contact discharge per IEC61000 4 2)



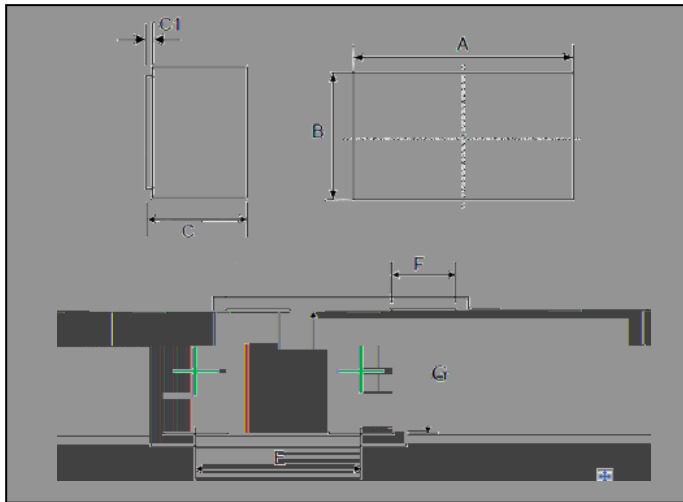
ESD clamping
(8kV contact discharge per IEC61000 4 2)



TLP Measurement

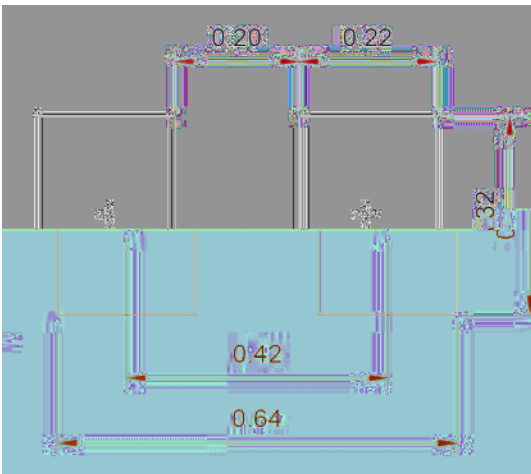


vDm



6 \ PER O	PLQ	PP	OD [
\$			
%			
&			
&			
(
)			
*			

vBm



Notes:

This recommended land pattern is for reference purposes only. Please consult your manufacturing group to ensure your PCB design guidelines are met



EB50

L

BA

Din